In the Claims:

Please cancel claims 1 to 9 without prejudice and add the following new claims 10 to 23:

Claims 1 to 9 (canceled).

10.(new) A circuit device for electrically connecting a wave guide (1) with a conductor strip (7), said conductor strip being arranged outside of the wave guide (1), wherein said circuit device comprises a contact element and said contact element consists of a prefabricated coil spring (11 to 14) having a first contacting area (9) and a second contacting area (9');

wherein said first contacting area (9) of said contact element is fixed to a surface of the wave guide (1) with an electrically conductive adhesive and said spring is pre-tensioned so that said second contacting area (9') of said contact element forms a sliding contact (10) in electrical contact with the conductor strip (7), but is slidable on the conductor strip (7); or

wherein said first contacting area (9) of said contact element is fixed to the conductor strip (7) with said electrically conductive adhesive and said spring is pre-tensioned so that the second contacting area (9') of said contact element forms a sliding contact (10) in electrical contact with the surface of the wave guide (1), but is slidable on the surface of the wave guide (1).

11.(new) The circuit device as defined in claim 10, wherein said coil spring (15) is a microgalvanic (MIGA) coil spring with a thickness of about 50 μm and a length

of from 100 to 200 μm.

12.(new) The circuit device as defined in claim 11, wherein said coil spring (15) is made with tolerances of ± 10 μm by UV depth lithography and multilayer galvanic methods in a batch production process.

13.(new) The circuit device as defined in claim 10, wherein said coil spring (15) is made by laser processing, high precision stamping or high precision punching.

14.(new) The circuit device as defined in claim 10, wherein said wave guide includes a stepping transformer and said surface of the wave guide is on the stepping transformer.

15.(new) The circuit device as defined in claim 10, further comprising a conductor strip substrate (2) and said conductor strip (7) is mounted on said conductor strip substrate (2).

16.(new) The circuit device as defined in claim 10, wherein said surface (1a) is on an exterior of the wave guide (1) and is perpendicular to the conductor strip (7).

17.(new) The circuit device as defined in claim 10, wherein said surface (1b) is inside a coupling opening (8) provided in the wave guide and is parallel to the

conductor strip (7).

18.(new) A circuit device for electrically connecting a wave guide (1) with a conductor strip (7), said conductor strip (7) being arranged outside of the wave guide (1), wherein said circuit device comprises a contact element and said contact element consists of a prefabricated U-shaped spring (15) having a first contacting area (9) and a second contacting area (9');

wherein said first contacting area (9) of said contact element is fixed to the conductor strip (7) with an electrically conductive adhesive and said second contact area (9') of said contact element comprises an electrically conductive adhesive area (16) connected with an exterior surface of the wave guide (1); or

wherein said first contacting area (9) of said contact element is fixed to the exterior surface of the wave guide (1) by said electrically conductive adhesive and said second contacting area (9') of said contact element comprises said electrically conductive adhesive area connected with the conductor strip (7).

19.(new) The circuit device as defined in claim 18, wherein said spring (15) is a microgalvanic (MIGA) coil spring with a thickness of about 50 μm and a length of from 100 to 200 μm.

20.(new) The circuit device as defined in claim 19, wherein said spring (15) is made with tolerances of ± 10 μm by UV depth lithography and multilayer galvanic methods in a batch production process.

21.(new) The circuit device as defined in claim 18, wherein said spring (15) is made by laser processing, high precision stamping or high precision punching.

22.(new) The circuit device as defined in claim 18, wherein said wave guide includes a stepping transformer and said exterior surface of the wave guide is on the stepping transformer.

23.(new) The circuit device as defined in claim 18, further comprising a conductor strip substrate (2) and said conductor strip (7) is mounted on said conductor strip substrate (2).